

PRINCE PROPERTY AND ASSESSMENT OF THE PROPERTY ASSE HLE-110-02-L-DV HLE-116-02-L-DV-K **HLE SERIES**

OTHER

OPTION

-BE = Bottom Entry

(N/A with -TE)

 $-\mathsf{A}$

= Alignment Pin (4 positions min.)

Metal or plastic at

Samtec discretion

(N/A with -TE, -PE & -LC)

–LC

= Locking Clip

(2 positions min.) (N/A with -A) (Manual placement

required)

= (6.50 mm) .256" DIA Polyimide Film Pick &

Place Pad

(3 positions min.) Not available

with -TE or

–PE tail option

_P

= Metal Pick &

Place Pad (3 positions min.)

> -TR = Tape & Reel

Packaging

(29 positions max.)

(3.86) .152

(7.11).280

(5.71) .225

(1.42)

(1.60)

.050

(1.27) .050

(2.54 mm) .100"

COST-EFFECTIVE RELIABLE SOCKET

Mates With:

TSW, MTSW, DW, EW, ZW, TLW, TSM, MTLW, HW

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?HLÉ

Insulator Material:

Black Liquid Crystal Polymer Contact Material:

Plating: Au or Sn over 50 μ" (1.27 μm) Ni Current Rating (HLE/TSM):

4.1 A per pin (2 pins powered)
Voltage Rating:
400 VAC

Operating Temp Range:

-55 °C to +125 °C Insertion Depth: (1.78 mm) .070" to (3.43 mm) .135", pass-through, or (2.59 mm) .102" min plus board thickness for

bottom entry **RoHS Compliant:**

PROCESSING

Lead-Free Solderable:

SMT Lead Coplanarity: (0.10 mm) .004" max (02-20) (0.15 mm) .006" max (21-50)* (.004" stencil solution may be available; contact IPG@samtec.com)

RECOGNITIONS

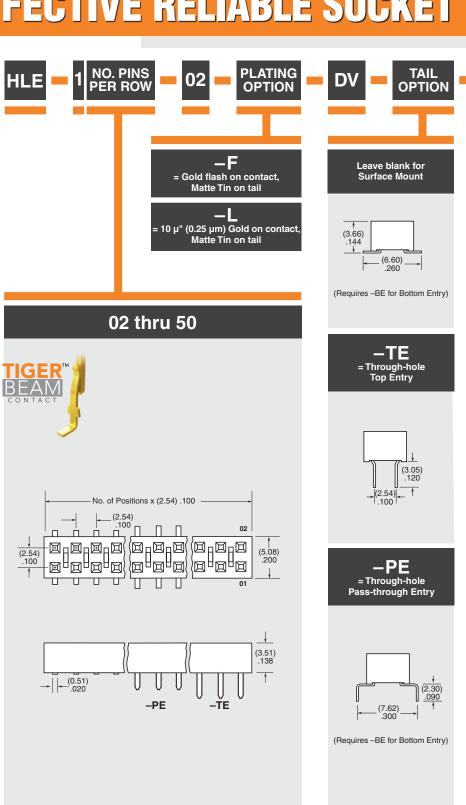
For complete scope of recognitions see www.samtec.com/quality



ALSO AVAILABLE (MOQ Required)

· Other platings

Some lengths, styles and options are non-standard, non-returnable.



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